

# XLA SOCKET

## NEXT-GENERATION XLA SOCKET TECHNOLOGY PROVIDES SUPERIOR WARPAGE CONTROL

TE Connectivity's (TE) distinctive new XLA socket technology enables you to customize your microprocessor to optimize the performance of your solutions. The XLA product line was developed for next generation data rates and can easily scale in size to align with technology trends. Our technology provides more reliable performance with superior warpage control compared to traditional molded socket technologies. TE can develop the entire solution including both socket and compression loaded hardware.

### Key Features

- Combines both PCB and stamped technologies
- Customizable to align with your design specifications in a one piece design
- Multiple configurations available including both LGA/BGA and LGA/LGA mounting styles

### Key Benefits

- Warpage control 78% better than traditional plastic housings
- 33% better true positioning on the solder ball and contact
- Low CTE mismatch to motherboard
- Validated to support 56 Gbps data rates

### Applications

- Servers
- Switches
- Optical Modules
- Interposers

## XLA Socket

### XLA Technology

56Gbps  
Validated

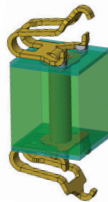
10,000+  
Pin counts

Up to  
110mm × 110mm

**Warpage (Min-Max):** 0.07mm - 0.09mm  
**Contact Side True Positioning:** 0.10mm

**Contact Deflection:** 0.32mm  
**Peak Normal Force (NF):** 34 gf

### Mounting Styles

LGA/ BGA (Hybrid)	LGA/ LGA (Dual Compression)
 <p><b>Pros</b></p> <ul style="list-style-type: none"><li>• Lower cost</li><li>• Lower profile</li><li>• Less vulnerable to pin damage</li></ul>	 <p><b>Pros</b></p> <ul style="list-style-type: none"><li>• Better deflection &amp; working range</li><li>• Easy field replacement</li></ul>

### Hardware Capabilities

TE has decades of experience developing compression hardware to ensure a reliable connection between the CPU and motherboard. Our hardware capabilities include independent loading mechanisms with formed levers, machined bolster plates and load cells to ensure a precise amount of load is equally distributed across the microprocessor, as well as minimizing the complexity to implement the hardware during your assembly process.

Please contact TE today so our experienced engineering teams can help design the socket needed for your next-generation application.

#### [te.com/products/LGA-Sockets](https://te.com/products/LGA-Sockets)

TE Connectivity, TE, TE Connectivity (logo) and Every Connection Counts are trademarks. All other logos, products and/or company names referred to herein might be trademarks of their respective owners.

The information given herein, including drawings, illustrations and schematics which are intended for illustration purposes only, is believed to be reliable. However, TE Connectivity makes no warranties as to its accuracy or completeness and disclaims any liability in connection with its use. TE Connectivity's obligations shall only be as set forth in TE Connectivity's Standard Terms and Conditions of Sale for this product and in no case will TE Connectivity be liable for any incidental, indirect or consequential damages arising out of the sale, resale, use or misuse of the product. Users of TE Connectivity products should make their own evaluation to determine the suitability of each such product for the specific application.

©2018 TE Connectivity Ltd. family of companies. All Rights Reserved.

1-1773956-5 06/18 DND

#### TE Technical Support Center

USA: 1.800.522.6752  
Canada: 1.905.475.6222  
Mexico: 52.0.55.1106.0800  
Latin/S. America: 54.0.11.4733.2200  
Germany: 49.0.6251.133.1999  
UK: 44.0.800.267666  
France: 33.0.1.3420.8686  
Netherlands: 31.0.73.6246.999  
China: 86.0.400.820.6015